


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	MICROCONTROLLERS/25/15269
1.3 Title of PCN	JSCC (China) STM32WB1x, STM32WB3x/5x, STM32WBA5x and STM32WL5x/LEx listed RF Products wire bonding conversion for UFQFPN5x5/7x7 and VFQFPN8x8 packages.
1.4 Product Category	STM32WB10xx, STM32WB15xx, STM32WB30xx, STM32WB35xx, STM32WB50xx, STM32WB55xx, STM32WBA50xx, STM32WBA52xx, STM32WBA54xx, STM32WBA55xx, STM32WL54xx, STM32WL55xx, STM32WLE4xx and STM32WLE5xx
1.5 Issue date	2025-06-20

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Direct Material: Bond Wire - Metallurgy (metallic composition/ raw material)	StatsChipPAC JSCC Jiangyin (China)

4. Description of change

	Old	New
4.1 Description	Assembly lines / wire bonding: - JSCC (China) / Gold wire - ATP (Philippines) for VQFN8x8 only / Gold wire	Assembly lines / wire bonding: - JSCC (China) / Copper Palladium wire additional source - JSCC (China) / Gold wire - ATP (Philippines) for VQFN8x8 only / Gold wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No change in Form, no change in Fit, no change in Function. Package darkness might change depending on molding compound. Pin1 identifier remain in the same corner but might slightly change in terms of form and positioning.	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end assembly line to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensure by ST internal tools
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7. Timing / schedule

7.1 Date of qualification results	2025-09-05
7.2 Intended start of delivery	2025-10-10
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	15269 MDRF-GPAM-RER2512 PCN15269 - JSCC STM32 RF products CuPd for QFPN5x5_7x7 and 8x8 packages - Reliability plan.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2025-06-20
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9. Attachments (additional documentations)
15269 Public product.pdf 15269 MDRF-GPAM-RER2512 PCN15269 - JSCC STM32 RF products CuPd for QFPN5x5_7x7 and 8x8 packages - Reliability plan.pdf 15269 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32WB10CCU5	
	STM32WB15CCU6	
	STM32WB15CCU6E	
	STM32WB30CEU5A	
	STM32WB35CCU6A	
	STM32WB35CCU7A	
	STM32WB35CEU6A	
	STM32WB35CEU7A	
	STM32WB50CGU5	
	STM32WB55CCU6	
	STM32WB55CCU7	
	STM32WB55CEU6	
	STM32WB55CEU6TR	
	STM32WB55CGU6	
	STM32WB55CGU6TR	
	STM32WB55CGU7	
	STM32WB55RCV6	
	STM32WB55RCV7	
	STM32WB55REV6	
	STM32WB55REV7	
	STM32WB55RGV6	
	STM32WB55RGV6TR	
	STM32WB55RGV7	
	STM32WBA50KGU6	
	STM32WBA52CEU6	
	STM32WBA52CGU6	
	STM32WBA52KEU6	
	STM32WBA52KGU6	
	STM32WBA54CEU6	
	STM32WBA54CEU7	
	STM32WBA54CGU6	
	STM32WBA54CGU7	
	STM32WBA54KGU6	
	STM32WBA55CEU7	
	STM32WBA55CGU6	
	STM32WL54CCU6	
	STM32WL55CCU6	
	STM32WL55CCU7	
	STM32WLE4C8U6	
	STM32WLE5C8U6	
	STM32WLE5CBU6	

	STM32WLE5CCU6	
	STM32WLE5CCU7	

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